2823

. Applicants:

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

T.L. Ritzdorf et al.

Attorney Docket No.: SEMT116049

Application No.: 09/018,783

Group Art Unit: 2823

Filed:

February 4, 1998

Examiner: D.M. Collins

Title:

METHOD FOR FILLING RECESSED MICRO-STRUCTURES WITH METALLIZATION IN THE PRODUCTION OF A MICROELECTRONIC

DEVICE

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Seattle, Washington 98101

May 25, 2001

TO THE COMMISSIONER FOR PATENTS:

Applicants are aware of the information listed in the attached form that may be material to the prosecution of the above-identified patent application.

- 1. X Copies of the listed patents, publications, and other information are enclosed for the Examiner's use.
- 2. X Pursuant to 37 C.F.R. § 1.97(b), this Information Disclosure Statement is being filed within three months of the filing date of the national application (other than a CPA), within three months of the date of entry of the national stage as set forth in 37 C.F.R. § 1.491 in an international application, before the mailing date of a first Office Action after the filing of an RCE.
- 3. X The Commissioner is hereby authorized to charge any fees under 37 C.F.R. §§ 1.16, 1.17 and 1.18 which may be required during the entire pendency of the application, or credit any overpayment, to Deposit Account No. 03-1740. This authorization also hereby includes a request for any extensions of time of the

LAW OFFICES OF
CHRISTENSEN O'CONNOR JOHNSON KINDNESSPULC
1420 Fifth Avenue
Suite 2800
Seattle, Washington 98101
206.682.8100

ire Recording Room appropriate length required upon the filing of any reply during the entire prosecution of this application. A copy of this document is enclosed.

Respectfully submitted,

CHRISTENSEN O'CONNOR JOHNSON KINDNESSPLLC

Marcia S. Kelbon

Registration No. 34,358

Direct Dial No. 206.695.1720

I hereby certify that this correspondence is being deposited with the U.S. Postal Service in a sealed envelope as first class mail with postage thereon fully prepaid and addressed to the Commissioner for Patents, Washington, D.C. 20231, on the below date.

Date:

May 25, 2001

MSK:mc